RELIABILITY REPORT

FOR MAX4495AUD+T

PLASTIC ENCAPSULATED DEVICES

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MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Conclusion

The MAX4495AUD+T successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX4493/MAX4494/MAX4495 single/dual/quad general-purpose operational amplifiers are designed for use in systems powered with dual supplies from ±2.25V to ±5.5V or with a single supply of +4.5V to +11V. These op amps provide a unity-gain bandwidth of 5MHz with only 770µA of quiescent current per amplifier. The wide input common-mode range extends from 200mV beyond the negative rail to within 1.5V of the positive supply rail while the output swings within 10mV (RL = 100k) of either rail. These amplifiers have excellent (110dB) open-loop gain with very low THD+N of 0.002% (f = 1kHz). The single MAX4493 is available in a tiny 5-pin SC70 package and the dual MAX4494 is available in the space-saving 8-pin SOT23. The quad MAX4495 is available in both 14-pin TSSOP and 14-pin SO packages. All products are rated at the automotive temperature range of -40°C to +125°C.

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II. Manufacturing Information

A. Description/Function:	SC70, Low-Power, General-Purpose, Dual-Supply, Rail-to-Rail Op Amps
B. Process:	CB2
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	October 27, 2001

III. Packaging Information

A. Package Type:	14-pin TSSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-2501-0087
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	110°C/W
K. Single Layer Theta Jc:	30°C/W
L. Multi Layer Theta Ja:	100.4°C/W
M. Multi Layer Theta Jc:	30°C/W

IV. Die Information

A. Dimensions:	59 X 64 mils
B. Passivation:	Si_3N_4 (Silicon nitride)
C. Interconnect:	Au
D. Backside Metallization:	None
E. Minimum Metal Width:	2 microns (as drawn)
F. Minimum Metal Spacing:	2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

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V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 150°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 80 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 13.74 \times 10^{-9}$

$\lambda = 13.74$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the CB2 Process results in a FIT Rate of 0.14 @ 25C and 2.48 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The OX47 die type has been found to have all pins able to withstand a HBM transient pulse of +/- 2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/- 250mA.

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Table 1
Reliability Evaluation Test Results

MAX4495AUD+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 150°C Biased Time = 192 hrs.	DC Parameters & functionality	80	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data

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